



CB : BOTTOM

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP
TO ANY BOARD.



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TITLE: TOP ASSEMBLY DRAWING

**LT3967 1.3A 8-SWITCH MATRIX LED DIMMER
WITH LT3960 I2C TO CAN-PHYSICAL TRANSCEIVER**

SIZE
N/A

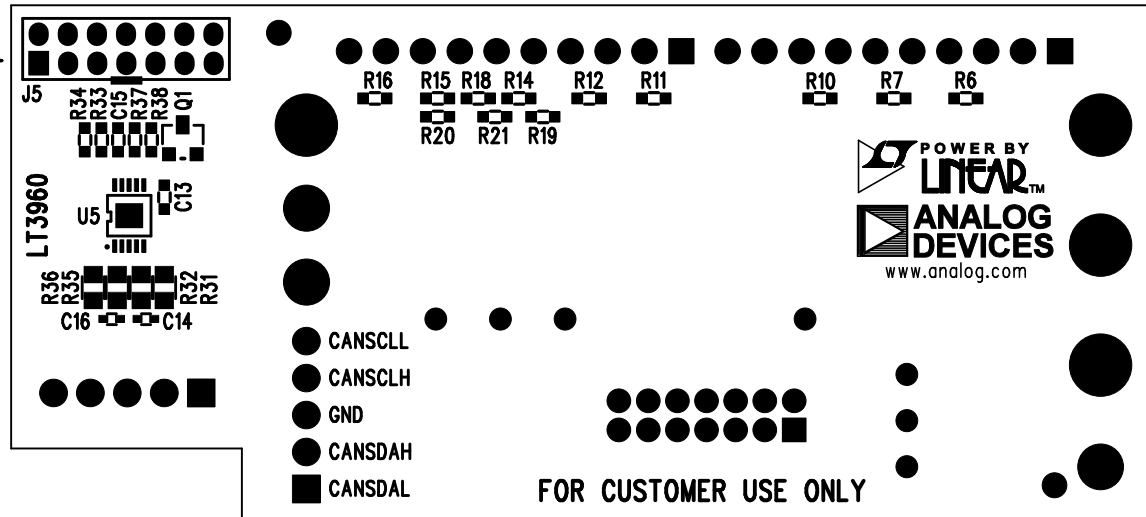
IC NO.

LT3967EFE/LT3960EMSE
DC2686A

REV.
5

SHT 1 OF 2

INSTALL J5 ON BOTTOM SIDE
MOLEX, 0791077006 (or equivalent)
2x7 SOCKET RECEPTICLE, 2mm



TITLE: BOTTOM ASSEMBLY DRAWING
LT3967 1.3A 8-SWITCH MATRIX LED DIMMER
WITH LT3960 I2C TO CAN-PHYSICAL TRANSCEIVER

SIZE	IC NO.	REV
N/A	LT3967EFE/LT3960EMSE DC2686A	5
		SHT 2 of 2